

Atty Docket No. JCLA8534

Serial No. 10/055,499

**REMARKS**

This is a full and timely response to the outstanding Final Office Action mailed October 20, 2004. Reconsideration and allowance of the application and presently pending claims are respectfully requested.

**1. Present Status of the Application**

Upon entry of the amendments in this response, claims 61-63, 70-81 and 83-89 remain pending in the present application.

**2. Response To Objections/Rejections**

Applicants respectfully traverse the rejections for at least the reasons set forth below.

**Response To Claim Rejections Under 35 U.S.C. Section 103**

The amended claim 61 reads as:

61. A chip packaging method comprising:  
*providing an organic substrate;*  
providing a plurality of dies, wherein each die has an active surface, a backside that is opposite to the active surface, and a plurality of metal pads located on the active surface;  
mounting the dies over the organic substrate, the backside of the dies facing the organic substrate;  
forming a plurality of patterned lines over the active surface of the dies; and  
*performing a singularizing process* to form multiple chip package structures, each having a single die or a plurality of dies.

*(emphasis added)*

Atty Docket No. JCLA8534

Serial No. 10/055,499

Saito et al. (US 5,049,980), Wachtler et al. (US 6,274,391) and Marcinkiewicz (US 6,025,099) disclose that only one multiple-chip module or single-chip module can be performed after performing the whole packaging processes. However, Eichelberger et al. (US 6,396,148) disclose that multiple chip modules can be performed at the same time after performing a singularizing process. These two packaging processes belong to different technical fields because one is used to fabricate only one chip module in one whole process but the other is used to fabricate multiple chip modules in one whole process. Therefore, applicants consider that the process taught by Saito, Wachtler and Marcinkiewicz can not be combined with the process taught by Eichelberger.

Eichelberger fails to teach, hint or suggest that the substrate carrying multiple chips can be organic. Even though Saito, Wachtler and Marcinkiewicz teach that the substrate carrying one or more chips can be organic, applicants consider that it is not ready for applying organic material to the substrate in the Eichelberger's packaging device because the packaging process taught by Saito, Wachtler and Marcinkiewicz and the packaging process taught by Eichelberger belong to different technical fields. Therefore, applicants consider that there is no evidence that it is sufficient to establish obviousness.

For at least the foregoing reasons, Applicant respectfully submits that the independent claim 61 patently define over the prior art references, and should be allowed. For at least the same reasons, dependent claims 62-63, 70-81 and 83-89 patently define over the prior art as well.

Atty Docket No. JCLA8534

Serial No. 10/055,499

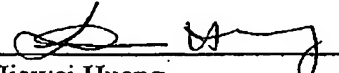
**CONCLUSION**

For at least the foregoing reasons, it is believed that the pending claims 61-63, 70-81 and 83-89 are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Date: 12/17/2004

4 Venture, Suite 250  
Irvine, CA 92618  
Tel.: (949) 660-0761

Respectfully submitted,  
J.C. PATENTS

  
Jiawei Huang  
Registration No. 43,330